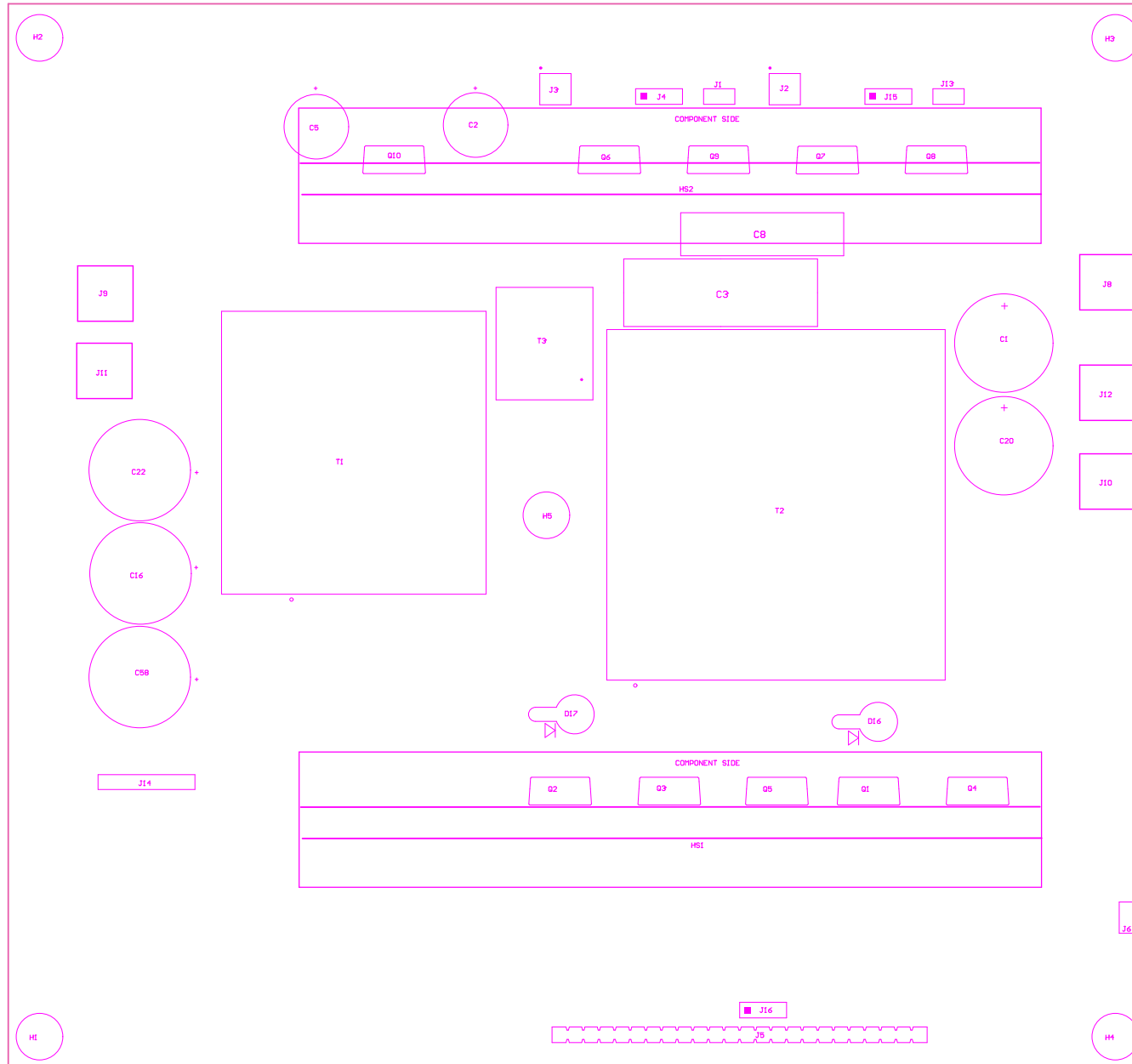
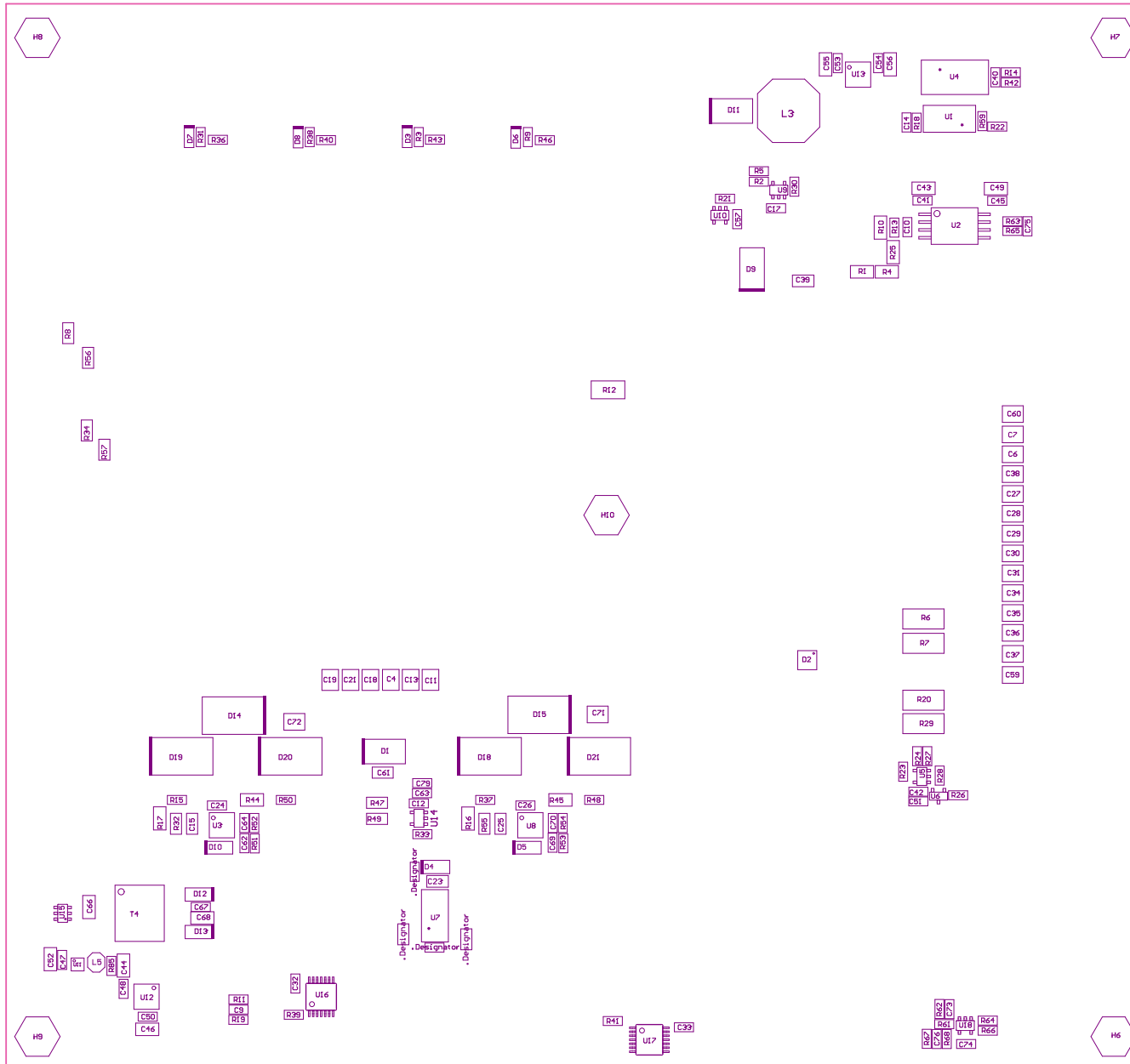


ZZ1 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.
 ZZ2 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
 ZZ3 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM TOP SIDE	BOARD #: TIDA-0095I	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = M5 Assembly Top	TID #: TIDA-0095I		
PLOT NAME = Top Assembly Drawing	GENERATED : 5/10/2017 8:07:25 PM	TEXAS INSTRUMENTS	



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.

ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM BOTTOM SIDE	BOARD #: TIDA-00951	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = M6 Assembly Bottom	TID #: TIDA-00951		
PLOT NAME = Bottom Assembly Drawing	GENERATED : 5/10/2017	8:07:26 PM	TEXAS INSTRUMENTS

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Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
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